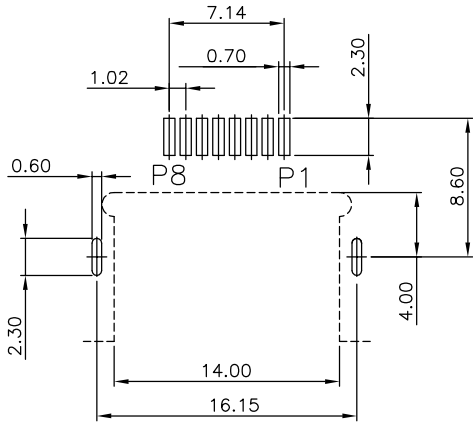
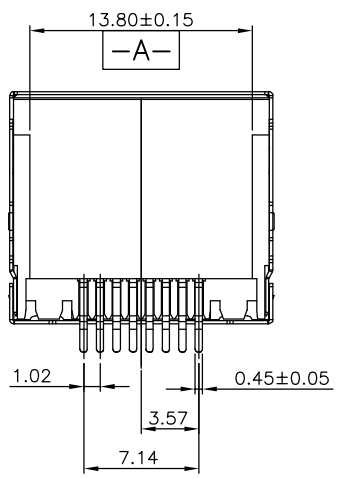
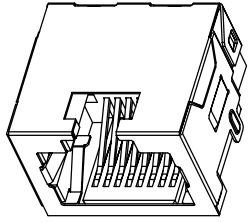
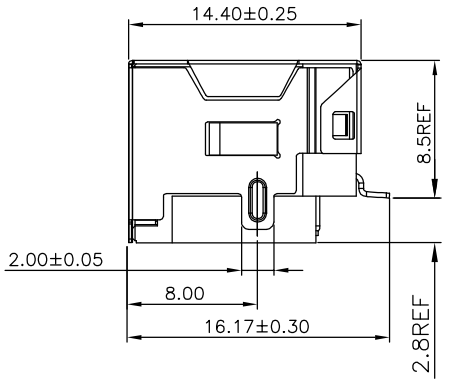
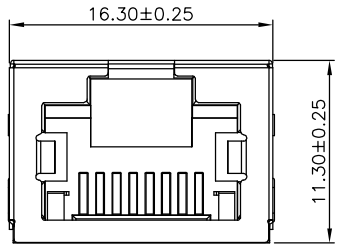


The product using material and processing must conform to the "WL-PZ-001"HSF technical standard control requirements



**PCB LAYOUT**  
TOL:±0.05

**NOTE:**

- MATERIAL SPECIFICATION:**
  - 1-1.HOUSING: LCP UL94V-0
  - 1-2.SHELL: 0.20mm BRASS
  - 1-3.CONTACT: PHOSPHOR BRONZE T=0.30MM
- PLATING SPECIFICATION:**
  - G/F PLATING OVER NI
  - 100u"SN PLATED ON SOLDER TALL AREA
  - 50u"NI UNDER PLATED OVER ALL
  - 2-1.SHELL: Ni 30U" MIN PLATING OVER ALL
- MECHANICAL PERFORMANCE:**
  - 3-1.INSERTION FORCE: 22N MAX
  - 3-2.REMOVAL FORCE: 22N MAX
  - 3-2.DURABILITY: 750 CYCLES MIN.
- ELECTRICAL PERFORMANCE:**
  - 4-1.CURRENT RATING:1.5A
  - 4-2.VOLTAGE RATING:125V MAX
  - 4-3.CONTACT RESISTANCE: 40mΩ Max.
  - 4-4.INSULATION RESISTANCE: 500MΩ MIN
  - 4-5.DIELECTRIC WITHSTANDING VOLTAGE: 500V AC Min
- ENVIRONMENTAL PERFORMANCE:**
  - OPERATING TEMPERATURE: -40°C~+85°C.
- PACKAGE SPEC:TRAY**

P/N:  
WLR4F9-08 8 X X X 024

PLATING:	HOUSING:
1-G/F	1-PBT
2-Au 3u"	2-LCP
3-Au 6u"	3-PA9T
5-Au 15u"	COLOUR:
6-Au 30u"	A-BLACK

REV.	REVISION RECORD	DATE	UNIT:mm	GENERAL TOLERANCES		SCALE: 1:1	NAME	DATE	PART.NO:	DWG.NO:		
A0	NEW RELEASE	21.01.13		SIZE: A4	LINEAR	ANGLES	APPROVED	Wang_jr	21.01.13	WLR4F9-088XXX024		ENDE05
				0.00±0.25	X°REF±6°		DESIGNER	Han_Gao	21.01.13			
				0.000±0.10	X°X' ±2°		DRAWN	Zijun_Huang	21.01.13	TITLE: RJ45 8P8C SMT沉板式8.5MM	REV: A0	SHEET: 1/1